

# PATENT ABSTRACTS OF JAPAN

(11)Publication number : 11-054884  
(43)Date of publication of application : 26.02.1999

(51)Int.CI. H05K 1/18  
H01L 21/60  
H01L 23/32  
H05K 3/34

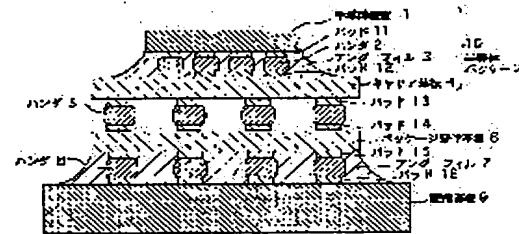
(21)Application number : 09-212065 (71)Applicant : NEC CORP  
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(54) MOUNTING STRUCTURE FOR SEMICONDUCTOR DEVICE

(57)Abstract:

**PROBLEM TO BE SOLVED:** To provide a mounting structure of the semiconductor device for mounting a semiconductor package with pair chips mounted thereon, and a large number of external thermals onto a printed circuit board through solder bump connections.

**SOLUTION:** In the structure of mounting a semiconductor package 10 onto a printed circuit board 9, a package-receiving board 6 whose outer size is nearly the same as or larger than the semiconductor package 10, having a pad 14 to be connected to the semiconductor package 10 on its upper face, and having a pad 15 to connect to a wiring board 9 at its lower side, is placed at a semiconductor conductor package-mounting position on the wiring board 9, the pad 16 of the wiring board 9 and the pad 15 at the lower face of the package-receiving board 6 are soldered by solder 8 and an under fill 7 is filled and fixed at the soldering part.



## LEGAL STATUS

[Date of request for examination] 06.08.1997

[Date of sending the examiner's decision of rejection] 11.04.2000

[Kind of final disposal of application other than the examiner's decision of rejection or application converted registration]

[Date of final disposal for application]

[Patent number]

[Date of registration]

[Number of appeal against examiner's decision 2000-06911  
of rejection]

[Date of requesting appeal against examiner's decision] 10.05.2000

decision of rejection]

[Date of extinction of right]

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